



## Product/Process Change Notice - PCN 15\_0048 Rev. -

Analog Devices, Inc. Three Technology Way Norwood, Massachusetts 02062-9106

This notice is to inform you of a change that will be made to certain ADI products (see Appendix A) that you may have purchased in the last 2 years. **Any inquiries or requests with this PCN (additional data or samples) must be sent to ADI within 30 days of publication date.** ADI contact information is listed below.

**PCN Title:** Conversion of 2x3mm LFCSP Package Outlines from Punch to Sawn and Transfer of Assembly Site to Amkor Philippines

**Publication Date:** 04-Nov-2015

**Effectivity Date:** 02-Feb-2016 *(the earliest date that a customer could expect to receive changed material)*

### Revision Description:

Initial Release

### Description Of Change

ADI is transferring the 2x3 Punch LFCSP from Amkor Korea to Amkor Philippines and will be converting to Sawn LFCSP. ADI had qualified Amkor Philippines standard bill of materials in a SAWN singulated leadframe. There will be a change in BOM for Die Attach Epoxy from Bell High Tech A3 to Ablestik 8290. Pin1 indicator will be laser marked as part of the change. See attached for changes and package outline differences.

### Reason For Change

ADI is transferring to Amkor Philippines due to Amkor Korea closure in 2016.

Sawn LFCSP is ADI's technology direction for LFCSP. The use of ADI qualified Amkor-Philippines as an assembly site will ensure continued source of product supply. ADI's assembly subcontractors manufacture our products using Analog Devices specified manufacturing flows, process controls and monitors. This assures that our customers receive the same level of quality and reliability on products they receive from qualified ADI manufacturing locations.

### Impact of the change (positive or negative) on fit, form, function & reliability

The devices function and reliability as specified by the product datasheet will be unaffected by these changes. The Lead Foot Print Dimension will remain the same for both punch and sawn LFCSP packages

### Summary of Supporting Information

Qualification has been performed per ADI0012, Procedure for Qualification of New or Revised Processes. See attached Qualification Results Summary.

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### Supporting Documents

**Attachment 1: Type:** Qualification Results Summary

ADI\_PCN\_15\_0048\_Rev\_-\_Qual Results Summary.pdf

**Attachment 2: Type:** Detailed Change Description

ADI\_PCN\_15\_0048\_Rev\_-\_BOM.pdf

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**For questions on this PCN, please send an email to the regional contacts below or contact your local ADI sales representatives.**

**Americas:** [PCN\\_Americas@analog.com](mailto:PCN_Americas@analog.com)

**Europe:** [PCN\\_Europe@analog.com](mailto:PCN_Europe@analog.com)

**Japan:** [PCN\\_Japan@analog.com](mailto:PCN_Japan@analog.com)

**Rest of Asia:** [PCN\\_ROA@analog.com](mailto:PCN_ROA@analog.com)

**Appendix A - Affected ADI Models****Added Parts On This Revision - Product Family / Model Number (13)**

AD8314 / AD8314ACPZ-RL7	AD8315 / AD8315ACPZ-REEL7	AD8317 / AD8317ACPZ-R2	AD8317 / AD8317ACPZ-R7	AD8319 / AD8319ACPZ-R2
AD8319 / AD8319ACPZ-R7	AD8353 / AD8353ACPZ-REEL7	AD8354 / AD8354ACPZ-REEL7	ADL5315 / ADL5315ACPZ-R2	ADL5315 / ADL5315ACPZ-R7
ADL5350 / ADL5350ACPZ-R2	ADL5350 / ADL5350ACPZ-R7	ADL5530 / ADL5530ACPZ-R7		

**Appendix B - Revision History**

<b>Rev</b>	<b>Publish Date</b>	<b>Effectivity Date</b>	<b>Rev Description</b>
Rev. -	04-Nov-2015	02-Feb-2016	Initial Release

Analog Devices, Inc.

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